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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
09/828,067	04/06/2001	Don E. Curry	005040/TCG/PMD/LE	7268
32588	7590	11/15/2006	EXAMINER	
APPLIED MATERIALS, INC. P. O. BOX 450A SANTA CLARA, CA 95052			ZERVIGON, RUDY	
		ART UNIT	PAPER NUMBER	
		1763		

DATE MAILED: 11/15/2006

Please find below and/or attached an Office communication concerning this application or proceeding.

Office Action Summary	Application No.	Applicant(s)	
	09/828,067	CURRY ET AL.	
	Examiner	Art Unit	
	Rudy Zervigon	1763	

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --
Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) OR THIRTY (30) DAYS, WHICHEVER IS LONGER, FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

Status

1) Responsive to communication(s) filed on 10 October 2006.
 2a) This action is **FINAL**. 2b) This action is non-final.
 3) Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

Disposition of Claims

4) Claim(s) 29-35 and 38-50 is/are pending in the application.
 4a) Of the above claim(s) _____ is/are withdrawn from consideration.
 5) Claim(s) _____ is/are allowed.
 6) Claim(s) 29-35 and 38-50 is/are rejected.
 7) Claim(s) _____ is/are objected to.
 8) Claim(s) _____ are subject to restriction and/or election requirement.

Application Papers

9) The specification is objected to by the Examiner.
 10) The drawing(s) filed on _____ is/are: a) accepted or b) objected to by the Examiner.
 Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).
 Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).
 11) The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

Priority under 35 U.S.C. § 119

12) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
 a) All b) Some * c) None of:
 1. Certified copies of the priority documents have been received.
 2. Certified copies of the priority documents have been received in Application No. _____.
 3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

* See the attached detailed Office action for a list of the certified copies not received.

Attachment(s)

1) <input type="checkbox"/> Notice of References Cited (PTO-892)	4) <input type="checkbox"/> Interview Summary (PTO-413)
2) <input type="checkbox"/> Notice of Draftsperson's Patent Drawing Review (PTO-948)	Paper No(s)/Mail Date. _____
3) <input type="checkbox"/> Information Disclosure Statement(s) (PTO/SB/08) Paper No(s)/Mail Date _____	5) <input type="checkbox"/> Notice of Informal Patent Application
	6) <input type="checkbox"/> Other: _____

DETAILED ACTION

Continued Examination Under 37 CFR 1.114

1. A request for continued examination under 37 CFR 1.114, including the fee set forth in 37 CFR 1.17(e), was filed in this application after final rejection. Since this application is eligible for continued examination under 37 CFR 1.114, and the fee set forth in 37 CFR 1.17(e) has been timely paid, the finality of the previous Office action has been withdrawn pursuant to 37 CFR 1.114. Applicant's submission filed on October 10, 2006 has been entered.

Claim Rejections - 35 USC § 103

2. The text of those sections of Title 35, U.S. Code not included in this action can be found in a prior Office action.

3. Claims 29, 30, 31, 33, 34, and 42-50 are rejected under 35 U.S.C. 103(a) as being unpatentable over Itsudo et al (JP05-198512) in view of Sivaramakrishnam; Visweswaren et al. (US 5,531,183 A). Itsudo teaches:

i. A wafer (2; Figure 6) processing apparatus (Figure 6, 8; abstract), comprising: a processing chamber (1; Figure 6; abstract) defined by a lower wall, an upper wall (8; Figure 6) and side walls extending from the lower wall to the upper wall (8; Figure 6), a wafer (2; Figure 6) supply opening (not shown; inherent) being formed in one of the walls for transferring a wafer (2; Figure 6) into the processing chamber (1; Figure 6; abstract); a susceptor (6; Figure 1) in the processing chamber (1; Figure 6; abstract) on which the wafer (2; Figure 6) can be located so that an upper surface of the wafer (2; Figure 6) faces the upper wall (8; Figure 6); a manifold (9; Figure 6) component located

on the processing chamber (1; Figure 6; abstract) and, together with the upper surface of the upper wall (8; Figure 6), defining a manifold cavity (9; Figure 6); an exhaust line (4; Figure 6) connected to the processing chamber (1; Figure 6; abstract), for flowing a gas from the processing chamber (1; Figure 6; abstract), connected such that the gas has a tendency to flow toward the exhaust line (4; Figure 6); and a processing gas supply line (12; Figure 6) connected to the manifold (9; Figure 6) component for providing a processing gas into the manifold cavity (9; Figure 6) wherein the processing gas comprises reactive gases used for processing the wafer – Applicant's claim requirement of gas identity, is an intended use claim requirement of the ending apparatus claims. Further, it has been held that claim language that simply specifies an intended use or field of use for the invention generally will not limit the scope of a claim (Walter, 618 F.2d at 769, 205 USPQ at 409; MPEP 2106). Additionally, in apparatus claims, intended use must result in a structural difference between the claimed invention and the prior art in order to patentably distinguish the claimed invention from the prior art. If the prior art structure is capable of performing the intended use, then it meets the claim (In re Casey, 152 USPQ 235 (CCPA 1967); In re Otto, 136 USPQ 458, 459 (CCPA 1963); MPEP 2111.02).

- ii. wherein the upper wall (8; Figure 6) of the processing chamber (1; Figure 6; abstract) comprises a plurality of processing gas supply openings (10; Figure 6, 8), each of the processing gas supply openings (10; Figure 6, 8) provide an intake opening (top surface of 8 at entrance of 10; Figure 6; abstract) into an upper surface of the upper wall (8; Figure 6) and an exhaust opening (bottom surface of 8 at exit of 10; Figure 6; abstract)

out of a lower surface of the upper wall (8; Figure 6) to provide a pathway for flowing processing gas from the manifold cavity (9; Figure 6) into the intake openings (top surface of 8 at entrance of 10; Figure 6; abstract) and out of the exhaust openings (bottom surface of 8 at exit of 10; Figure 6; abstract) of the processing gas openings (10; Figure 6, 8) in the upper wall (8; Figure 6), and into the processing chamber (1; Figure 6; abstract), the processing gas supply openings (10; Figure 6, 8) being nonuniformly (Figure 8) distributed over the upper wall (8; Figure 6) to create a flow pattern comprising a predominantly vertical flow of processing gas onto the wafer, as claimed by claim 29 – When the structure recited in the reference is substantially identical to that of the claims, claimed properties or functions are presumed to be inherent (In re Best, 562 F.2d 1252, 1255, 195 USPQ 430, 433 (CCPA 1977); MPEP 2112.01).

- iii. The apparatus (Figure 6, 8; abstract) of claim 29 wherein the openings (10; Figure 6, 8) are more densely located on one side of the upper wall (8; Figure 6) than on another side thereof, as claimed by claim 30
- iv. The apparatus (Figure 6, 8; abstract) of claim 30 wherein the openings (10; Figure 6, 8) are substantially equal in size, as claimed by claim 31
- v. The apparatus (Figure 6, 8; abstract) of claim 29 wherein the exhaust line (4; Figure 6) is connected at an exhaust location which is off-center with respect to a center point (geometric center of 8; Figure 8) of the wafer (2; Figure 6), when viewed from above, so that the gas exits out of the processing chamber (1; Figure 6; abstract) at the exhaust location which is off-center with respect to a center point (geometric center of 8; Figure 8) of the wafer (2; Figure 6), as claimed by claim 33

vi. The apparatus (Figure 6, 8; abstract) of claim 33 wherein a channel (present, not labelled; Figure 1) is defined within the processing chamber (1; Figure 6; abstract), wherein the channel (present, not labelled; Figure 1) is concentric with the wafer (2; Figure 6), wherein the processing gas flows radially outwardly over the wafer (2; Figure 6) into the channel (present, not labelled; Figure 1), from the channel (present, not labelled; Figure 1), to the exhaust location into the exhaust line (4; Figure 6), as claimed by claim 34 – When the structure recited in the reference is substantially identical to that of the claims, claimed properties or functions are presumed to be inherent (In re Best, 562 F.2d 1252, 1255, 195 USPQ 430, 433 (CCPA 1977); MPEP 2112.01).

vii. A wafer (2; Figure 6) (2; Figure 6) processing apparatus (Figure 6, 8; abstract), comprising: a processing chamber (1; Figure 6; abstract) defined by a lower wall, an upper wall (8; Figure 6) and side walls extending from the lower wall to the upper wall (8; Figure 6); a susceptor (6; Figure 1) in the processing chamber (1; Figure 6; abstract) on which the wafer (2; Figure 6) can be located so that an upper surface of the wafer (2; Figure 6) faces the upper wall (8; Figure 6); a manifold (9; Figure 6) component located on the processing chamber (1; Figure 6; abstract) and, together with the upper surface of the upper wall (8; Figure 6), defining a manifold cavity (9; Figure 6); an exhaust system comprising an exhaust line (4; Figure 6) connected to the processing chamber (1; Figure 6; abstract), for flowing an exhaust gas from the processing chamber (1; Figure 6; abstract); a processing gas supply line (12; Figure 6) connected to the manifold (9; Figure 6) component; a plurality of processing gas supply openings (10; Figure 6, 8) distributed non-uniformly in the upper wall (8; Figure 6) providing a means for supplying a

processing gas from the manifold cavity (9; Figure 6) to the processing chamber (1; Figure 6; abstract), wherein the processing gas comprises non-depleted reactive gases used for processing the wafer (2; Figure 6), wherein the exhaust gas comprises reacted gases and depleted processing gas, wherein the processing gas supply openings (10; Figure 6, 8) may be non-uniformly distributed over the upper wall (8; Figure 6), wherein the processing gas supply openings (10; Figure 6, 8), the manifold cavity (9; Figure 6) and component, processing gas supply, and exhaust system predominantly determine the flow pattern of processing gas onto the upper surface of the wafer (2; Figure 6), as claimed by claim 42

- viii. The apparatus of claim 42, wherein the exhaust line (4; Figure 6) is connected at an exhaust location which is off-center with respect to a center point of the wafer (2; Figure 6), when viewed from above, so that the processing gas exits out of the processing chamber (1; Figure 6; abstract) at the exhaust location which is off-center with respect to a center point of the wafer (2; Figure 6), as claimed by claim 43
- ix. The apparatus of claim 42, wherein the processing gas openings comprises openings on the manifold cavity (9; Figure 6) side of the upper wall (8; Figure 6) that differ in location and/or direction than the corresponding openings on the processing chamber (1; Figure 6; abstract) side of the upper wall (8; Figure 6), as claimed by claim 44
- x. The apparatus of claim 42, wherein the processing gas supply openings (10; Figure 6, 8) create a predominately vertical flow pattern of processing gas onto the upper surface of the wafer (2; Figure 6), as claimed by claim 45

- xi. The apparatus of claim 42, wherein the processing gas provided into the processing chamber (1; Figure 6; abstract) enters predominantly through the processing gas supply openings (10; Figure 6, 8), as claimed by claim 46
- xii. A wafer (2; Figure 6) (2; Figure 6) processing apparatus (Figure 6, 8; abstract), comprising: a processing chamber (1; Figure 6; abstract) defined by a lower wall, an upper wall (8; Figure 6) and side walls extending from the lower wall to the upper wall (8; Figure 6); a susceptor (6; Figure 1) in the processing chamber (1; Figure 6; abstract) on which the wafer (2; Figure 6) can be located so that an upper surface of the wafer (2; Figure 6) faces the upper wall (8; Figure 6); a manifold (9; Figure 6) component located on the processing chamber (1; Figure 6; abstract) and, together with the upper surface of the upper wall (8; Figure 6), defining a manifold cavity (9; Figure 6); a processing gas supply line (12; Figure 6) connected to the manifold (9; Figure 6) component; a plurality of processing gas supply openings (10; Figure 6, 8) in the upper wall (8; Figure 6), wherein a processing gas from the manifold cavity (9; Figure 6) passes into the processing chamber (1; Figure 6; abstract), wherein the processing gas comprises reactive gases used for processing the wafer (2; Figure 6), wherein the processing gas supply openings (10; Figure 6, 8) are non-uniformly distributed over the upper wall (8; Figure 6), and an exhaust system comprising an exhaust line (4; Figure 6) connected to the processing chamber (1; Figure 6; abstract), for flowing an exhaust gas from the processing chamber (1; Figure 6; abstract), wherein the exhaust gas comprises reacted gases and depleted processing gas, as claimed by claim 47

- xiii. The apparatus of claim 47, wherein the processing gas provided into the processing chamber (1; Figure 6; abstract) enters predominantly through the processing gas supply openings (10; Figure 6, 8) , as claimed by claim 48
- xiv. The apparatus of claim 47, further comprising a chamber within the processing chamber (1; Figure 6; abstract), wherein the channel is concentric and below the wafer (2; Figure 6), wherein the processing gas flows radially outwardly over the wafer (2; Figure 6) and into the channel, and then from the chamber to the exhaust location and into the exhaust line (4; Figure 6) , as claimed by claim 49
- xv. The apparatus of claim 49, wherein the inner diameter of the channel is comparable to or slightly less than the outer diameter of the wafer (2; Figure 6) , as claimed by claim 50

Itsudo does not teach a gas supply line connected via a processing gas supply line opening formed through an upper surface of the manifold cavity.

Sivaramakrishnam teaches a gas supply (40,60,80; Figure 2) connected via a processing gas supply line opening formed through an upper surface (top of 10) of a manifold cavity (38).

It would have been obvious to one of ordinary skill in the art at the time the invention was made to add Sivaramakrishnam's gas supplies and for Itsudo to optimize the relative location of his processing gas supply line opening.

Motivation to add Sivaramakrishnam's gas supplies and for Itsudo to optimize the relative location of his processing gas supply line opening is to use process gas sources as precursors for operations and to optimize desired process gas flows as taught by Itsudo (abstract). It is well established that the rearrangement of parts is considered obvious to those of ordinary skill (In re Japikse , 181 F.2d 1019, 86 USPQ 70 (CCPA 1950); In re Kuhle , 526 F.2d 553, 188 USPQ 7

(CCPA 1975); Ex parte Chicago Rawhide Manufacturing Co. , 223 USPQ 351, 353 (Bd. Pat. App. & Inter. 1984); MPEP 2144.04)

4. Claims 32, 35, 38, 39, and 40 are rejected under 35 U.S.C. 103(a) as being unpatentable over Itsudo et al (JP05-198512) and Sivaramakrishnam; Visweswaren et al. (US 5,531,183 A) in view of Nguyen, Tue (US 6,444,039 B1). Itsudo and Sivaramakrishnam are discussed above. Itsudo further teaches Itsudo's apparatus (Figure 6, 8; abstract) of claim 40 wherein Itsudo's openings (10; Figure 6, 8) are formed to increase a flow rate of Itsudo's gas over Itsudo's wafer (2; Figure 6) farther from Itsudo's exhaust location, as claimed by claim 41 – When the structure recited in the reference is substantially identical to that of the claims, claimed properties or functions are presumed to be inherent (In re Best, 562 F.2d 1252, 1255, 195 USPQ 430, 433 (CCPA 1977); MPEP 2112.01).

Itsudo and Sivaramakrishnam do not teach:

- i. Itsudo's apparatus (Figure 6, 8; abstract) of claim 29 wherein flow of gas in Itsudo's processing chamber (1; Figure 6; abstract) is laminar, as claimed by claim 32
- ii. Itsudo's apparatus (Figure 6, 8; abstract) of claim 34 wherein Itsudo's openings (10; Figure 6, 8) are more densely located farther from Itsudo's exhaust location, as claimed by claim 35
- iii. Itsudo's apparatus (Figure 6, 8; abstract) of claim 29 wherein the intake openings (top surface of 8 at entrance of 10; Figure 6; abstract) and the exhaust openings (bottom surface of 8 at exit of 10; Figure 6; abstract) of Itsudo's processing gas openings (10; Figure 6, 8) on opposing sides of a point (geometric center of 8; Figure 8) on Itsudo's upper wall (8; Figure 6), have the exhaust opening (bottom surface of 8 at exit of 10;

Figure 6; abstract) of one opening which is angularly displaced relative to the intake opening (top surface of 8 at entrance of 10; Figure 6; abstract) of the one opening thereof in a selected direction about Itsudo's point (geometric center of 8; Figure 8), and Itsudo's second opening having the exhaust opening (bottom surface of 8 at exit of 10; Figure 6; abstract) which is angularly displaced relative to the intake opening (top surface of 8 at entrance of 10; Figure 6; abstract) thereof in Itsudo's selected direction, so that Itsudo's openings (10; Figure 6, 8) jointly create a circular gas flow pattern in Itsudo's processing chamber (1; Figure 6; abstract), as claimed by claim 38 – Applicant's Figure 4, 5 embodiment

- iv. Itsudo's apparatus (Figure 6, 8; abstract) of claim 38 wherein a third of Itsudo's openings (10; Figure 6, 8), on a side of Itsudo's second opening opposing Itsudo's first opening, has an exhaust opening (bottom surface of 8 at exit of 10; Figure 6; abstract) which is displaced in Itsudo's first direction relative to an intake opening (top surface of 8 at entrance of 10; Figure 6; abstract) thereof, as claimed by claim 39
- v. Itsudo's apparatus (Figure 6, 8; abstract) of claim 29 wherein Itsudo's processing gas in the manifold cavity (9; Figure 6) comprises non-depleted reactive gases used for processing the wafer, as claimed by claim 40 – However, gas identity is not considered a structural limitation in the pending apparatus claims. Further, it has been held that claim language that simply specifies an intended use or field of use for the invention generally will not limit the scope of a claim (Walter, 618 F.2d at 769, 205 USPQ at 409; MPEP 2106). Additionally, in apparatus claims, intended use must result in a structural difference between the claimed invention and the prior art in order to patentably

distinguish the claimed invention from the prior art. If the prior art structure is capable of performing the intended use, then it meets the claim (In re Casey, 152 USPQ 235 (CCPA 1967); In re Otto, 136 USPQ 458, 459 (CCPA 1963); MPEP2111.02).

Nguyen teaches a portion (vertical part) of a gas distribution plate (111; Figure 10) including injection holes (117, Figure 10) with Applicant's claimed angular displacement as per Applicant's Figures 4, 5.

It would have been obvious to one of ordinary skill in the art at the time the invention was made to angle Itsudo's processing gas supply openings (10; Figure 6, 8) as taught by Nguyen, further to process the wafer under laminar flow including optimized hole distributions as taught by Itsudo.

Motivation to angle Itsudo's processing gas supply openings (10; Figure 6, 8) as taught by Nguyen, further to process the wafer under laminar flow including optimized hole distributions as taught by Itsudo is for influencing flow patterns of Itsudo's process gases to achieve controlled CVD film thickness distributions as taught by Itsudo (abstract).

Response to Arguments

5. Applicant's arguments filed October 10, 2006 have been fully considered but they are not persuasive.
6. Applicant states that the Examiner's above combination would not have a reasonable expectation for success and render the combination "inoperable". Applicant's position is based upon "Itsudo par. [0002], which discloses that a purging inert gas is used in the light source chamber 29 to prevent dirt deposits on the perforated plate....Therefore, if processing gas is introduced into the light source chamber, as proposed in the rejection of the Office Action, then

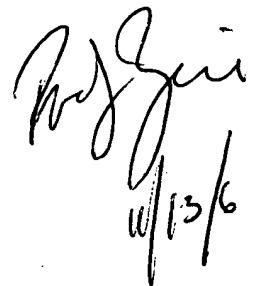
the light source, having a suitable wavelength for photochemical reaction with the processing gas would cause the processing gas in the light source chamber to react and form deposits inside the light source chamber. These deposits would quickly cover the light source and the quartz perforated plate, preventing the light to reach the processing chamber, rendering the apparatus inoperable. ”. However, as the Examiner has repeatedly demonstrated, gas identity does not distinguish the pending apparatus claims from the prior art. Applicant’s recited properties for an otherwise unknown “processing gas” does not structurally distinguish the apparatus of Itsudo from the apparatus claims of the pending application. Applicant’s inoperability assumes that there is no gas in existence, suitable under MPEP 2144.07, that would *not* “react and form deposits inside the light source chamber” based on numerous possible light source wavelengths. The Examiner rejects this position. Further the reactivity of a process gas in the Itsudo apparatus would also depend on the particular light source characteristics, residence time (flow rate), and even concentration. Even *if* Itsudo would inject a reactive gas that would “cover the light source and the quartz perforated plate”, the apparatus would, depending on the above conditions, continue depositing films on the wafer until or if the light source and the quartz perforated plate were coated sufficiently to need replacement or cleaning.

Conclusion

7. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Examiner Rudy Zervigon whose telephone number is (571) 272-1442. The examiner can normally be reached on a Monday through Thursday schedule from 8am through 7pm. The official fax phone number for the 1763 art unit is (571) 273-8300. Any Inquiry

Art Unit: 1763

of a general nature or relating to the status of this application or proceeding should be directed to the Chemical and Materials Engineering art unit receptionist at (571) 272-1700. If the examiner can not be reached please contact the examiner's supervisor, Parviz Hassanzadeh, at (571) 272-1435.



A handwritten signature in black ink, appearing to read "Parviz Hassanzadeh". Below the signature, the date "10/13/06" is handwritten in a smaller, more vertical style.